

Compression Molding System

Model CPM1080-HP



**New compression molding system achieving high precision
and high productivity for WLP/PLP molding processes**



English

New compression molding system achieving high precision and high productivity for WLP/PLP molding processes

- Ideal for advanced packages such as HBM/2.5D/3D/Chiplet, as well as FOWLP/PLP.
- Realization of wafer level molding/panel level molding based on proprietary compression technology.
- Features a unique uniform resin dispersion and pattern dispense system, effectively catering to both thin and thick molding requirements as well as MUF filling needs.
- Enhances mold thickness flatness and achieves higher vacuum levels, resulting in higher quality production.
- The film consumption is reduced by 25% by precutting system. (Compared to our product)
- Modular concept to adapt to different production quantities.



SPECIFICATION

Items			Unit	Description			
Model			—	CPM1080-HP			
Workpiece type			—	Panel・Wafer			
Workpiece size	Panel		mm	□150—320mm			
	Wafer		mm	φ 320 (Max.)			
Molding compound			—	Granular・Liquid			
Machine time			sec	Approximately 65			
External dimensions	Number of press modules		module	1	2	3	4
	Width		mm	5,490	6,170	6,850	7,530
	Depth		mm	2,168	2,168	2,168	2,168
	Height	Granular resin specification	mm	1,980	1,980	1,980	1,980
		Liquid resin specification	mm	2,170	2,170	2,170	2,170
Weight			ton	10.2	13.8	17.4	21.0
Number of workpieces per cycle			workpiece	1	2	3	4
Magazine setting space			—	Panel : Input／Output 2 cassette each Wafer : 2 loadport			
Clamp capacity			kN／(tf)	98.0—784.0／10.0—80.0			
Clamp speed			mm／sec	100 (Max.)			
Release film width			mm	440 (Max.)			
Option	Chip count		—	○			
	Package inspection		—	○			
	Package thickness measurement		—	○			
	After cure		—	○			
	Film handler		—	○			
	Substrate preheater		—	○			

・ The figures shown above are based on standard machine specifications.
 ・ The above specification are subject to change without prior notice.
 ・ For special requirements, please consult your local TOWA representative.



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